

### In The Specification

Please make the following changes to paragraph [0018]:

[0018] The first device portion 4 includes a first flag first receiving area for a die 12 surrounded by first bond pads 16 and first ground pads 17. The first flag 12 is not limited to the rectangular shape shown in FIG. 1. Instead, the first flag 12 may be an open window within the leadframe 10, "X-shaped", or the like. Furthermore, the first flag may be elevated or indented relative to other areas of the leadframe 10. In the embodiment illustrated, the first bond pads 16 are parallel to the sides of the first flag 12 and the first ground pads 17 are located at the four corners of the first flag 12. (Only two sets of the first bond pads 16 are numbered to avoid cluttering the figures. However, all three boxes between the first ground pads 17 on each side of the first flag 12 are bond pads.) In addition, a skilled artisan should recognize that the number of first bond pads 16 drawn and their configuration is illustrative only. Any number of first bond pads 16 may be present and each side of the first flag 12 may not have identical numbers of first bond pads 16. Furthermore, the first bond pads 16 may be staggered relative to each other along each side of the first flag 12 or any other suitable configuration may be used. Also, the first ground pads 17 can have a different configuration or location.

Please make the following changes to paragraph [0032]:

[0032] The conductive layer 42 can be deposited by physical vapor deposition (PVD), chemical vapor deposition (CVD), atomic layer deposition (ALD), electrolytic plating, electroless plating, flame spray, conductive paint spray, vacuum metallization, pad printing, the like, or combinations of the above. The conductive layer 42 is preferably approximately ~~X-Y units in thickness, or more preferably~~ 1 to 50 microns in thickness; the thickness of the conductive layer 42 will depend upon the shielding effectiveness desired. The minimum thickness of the conductive layer 42 depends on the process used to form the conductive layer 42 and the maximum thickness depends on the amount of stress of the conductive layer 42, which is a function of at least the material being used.

### Remarks

Amendments to the specification are made to fix errors. No new matter is added.

### **Restriction**

The Examiner restricted pending claims 1-24 into four groups: Groups I (claims 1-8), II (claims 9-15), III (claims 16-19), and IV (claims 20-24). Applicants believe this restriction is improper because all of the groups are not independent or distinct from each other. More specifically, Applicants submit that Groups I and IV are not independent and distinct from each other.

Group I is directed to a product and Group IV is directed to a method. The Examiner contends that the Groups I and IV are distinct because the product as claimed in Group I can be made by another and materially different process because Group "I does not require the use of a wire to couple the leadframe to the conductive layer..." Applicants submit the Examiner is in error. Independent claim 1 of Group I states, in line 6, "a wire electrically coupling the leadframe to the conductive layer." Therefore, both Group I and Group IV include the feature of a wire to couple the leadframe to the conductive layer. For at least this reason, the claims of Groups I and IV are not independent and distinct. Therefore, the restriction between the claims of Group I and IV is in error.

In addition, the search and examination of all claims would not be a serious burden on the Examiner. The Examiner will inherently search the subject matter included within the claims of Group I when he searches the claims of Group IV. Accordingly, examination of all the claims is not a serious search burden on the Examiner. Therefore, the Examiner must examine the entire application on the merits even if it includes claims to independent and distinct inventions.

M.P.E.P. § 803.

Therefore, Applicants submit the Examiner should find that the proper restriction should be only three Groups, not four as the Examiner contended:

- 1) Claims 1-8 and 20-24 (previously, Groups I and IV);
- 2) Claims 9-15 (Group II), and
- 3) Claims 16-19 (Group III).

Therefore, Applicants will choose to prosecute the claims of the pending application to claims 1-8 and 20-24 (Groups I and IV according to the Examiner's classification).

However, if the Examiner still contends that the claims of Groups I and IV are independent or distinct as well as the claims of Groups II and III, Applicants chose to prosecute the claims of Group I.